

The Office Action rejects claims 1, 2 and 5-7 under 35 U.S.C. §102(b) over U.S. Patent Publication No. 2002/0125556 to Oh et al. ("Oh"); and rejects claims 3 and 4 under 35 U.S.C. §103(a) over Oh in view of U.S. Patent No. 6,472,758 to Glenn et al. ("Glenn"). These rejections are respectfully traversed.

As discussed during the personal interview, Oh discloses a method in which a liquid phase adhesive 3 is hardened before a second semiconductor chip 2 is mounted on a first semiconductor 1. See Fig. 1 and paragraph 0064. Oh does not disclose or suggest that the adhesive 3 is a liquid resin, or that a liquid resin is hardened after the second semiconductor chip is mounted on the first semiconductor chip. Thus, Oh does not disclose mounting a second semiconductor chip over a first semiconductor chip through a liquid resin, or hardening the liquid resin to form a spacer between the first semiconductor chip and the second conductor chip, as recited in claim 1. Thus, Oh does not disclose each and every element recited in claim 1.

Furthermore, as discussed during the personal interview, the method recited in claim 1 simultaneously forms a spacer and fixes the first and second semiconductor chips together in a single step of hardening the liquid resin. See the specification at, for example, paragraph 0004. Oh does not recognize such an advantage. Thus, Oh does not even suggest the subject matter recited in claim 1.

Glenn does not disclose or suggest mounting a second semiconductor chip over a first semiconductor chip through a liquid resin, or hardening the liquid resin to form a spacer between the first semiconductor chip and the second semiconductor chip, as recited in claim 1. Thus, Glenn does not supply the subject matter lacking in Oh.

In view of the above, Oh and Glenn, either individually or in combination, do not disclose or suggest the subject matter recited in claim 1, and claims 2-7 depending therefrom.

Accordingly, withdrawal of the rejections of claims 1-7 under 35 U.S.C. §102(b) and §103(a) is respectfully requested.

Claims 8-10 are also patentable at least in view of the patentability of claim 1, from which they depend, as well as for additional features they recite. Thus, rejoinder of claims 8-10 is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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